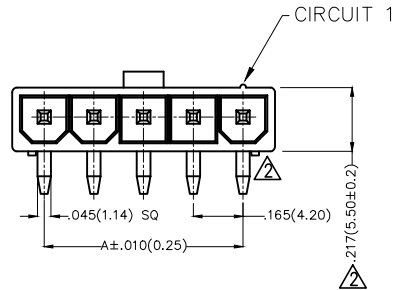


REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD
1		Change the height of 3 circuits to be the same as other circuits.	05/JUL/19	KATE	CHERRY
2		Structure & Size change	23/MAR/22	MATT	CHERRY
3		Flammability Change	17/MAY/24	KATE	LEO

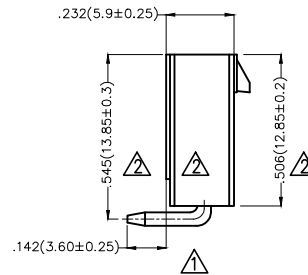
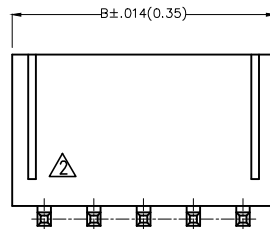


Electrical

Current Rating: 9A AC(rms)/DC
Voltage Rating: 250V AC(rms)/DC
Contact Resistance: 15 mΩ Max
Insulation Resistance: 1000 MΩ MIN
Withstanding Voltage: 1500V AC r.m.s
Temperature Range—Operating: -25°C~+85°C

Material and Plating

Housing: PA66(UL 94V-2)
Contact Pin: Brass
Plating: Tin Plated

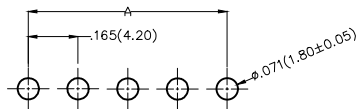


Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B
2	FWF42007-S02B22TK	.165(4.20)	.386(9.80)
3	FWF42007-S03B22TK	.331(8.40)	.551(14.00)
4	FWF42007-S04B22TK	.496(12.60)	.717(18.20)
5	FWF42007-S05B22TK	.661(16.80)	.882(22.40)

Ordering Information

FWF 420 07 — S XX B 2 2 T K
1 2 3 4 5 6 7 8 9 10

1	Category FWF—Wafer	2	Series Number 420—Pitch4.2mm	3	Distinction No. 07	4	Row Option S—Single Row	5	Circuits XX	6	Entry Angle B—90° Angle
7	Plating 2—Tin Plated	8	Material—Resin 2—PA66	9	Color—Resin T—Transparent	10	Packaging K—Tray				



Recommended P.C.Board Layout

 THIRD ANGLE PROJECTION		GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 28/JUN/13	PART NO. FWF42007-SXXB22TK	ITEM NO. FWF42007	 Leader Of Industry	
		X.±.012(0.30)	X.±5°	CHECKED BY	DATE	TITLE			
DESIGN UNITS Inch (metric)		X.X±.008(0.20)	.X±2°	JACOB	28/JUN/13	Wire to Board (Wafer) Pitch 4.2mm 90° Angle (DIP)		REV 3	SHEET NO. 1/1
SCALE 5:1	SIZE A4	X.XX±.006(0.15)	.XX±1°	DRAWN BY	DATE	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		X.XXX±.004(0.10)	.XXX±0.5°	CHERRY	28/JUN/13				